The attempt of using GaN (Cs) as a photocathode in SRF injector





N generated electrons

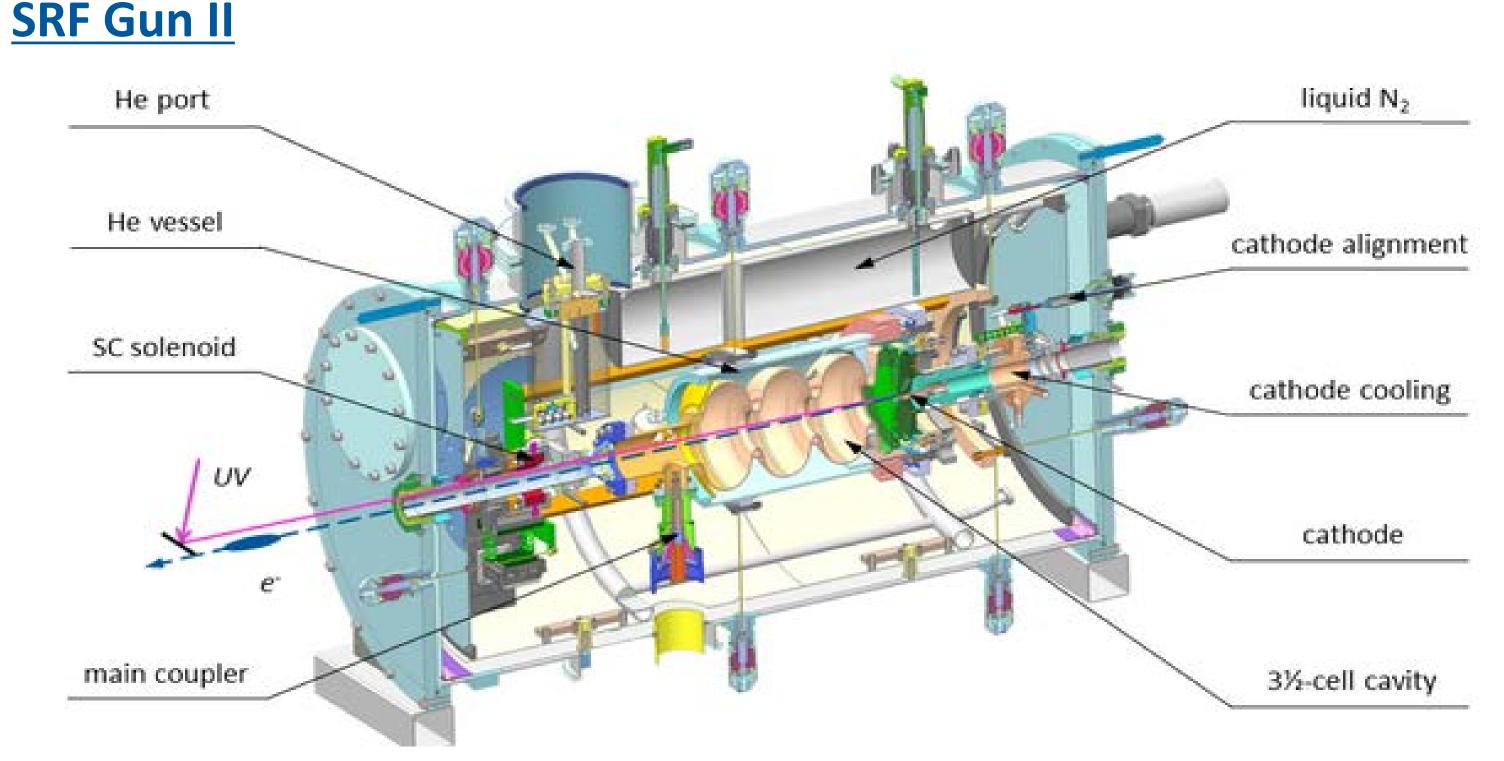
N incident photons

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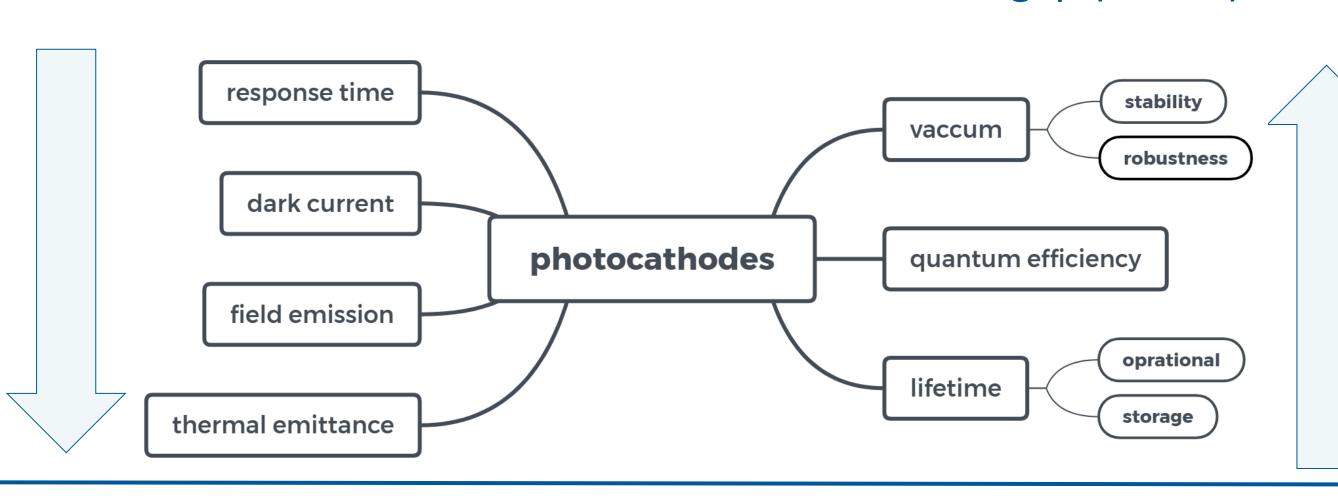


1. Introduction



desireable requirements for photocathodes

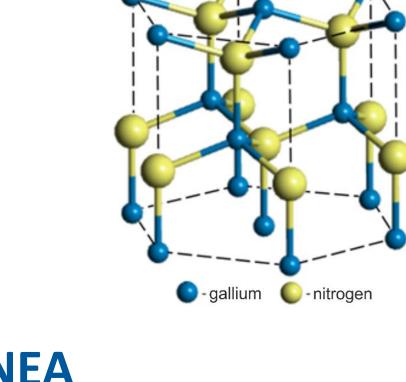
- searching for better photocathodes is one of the principle challenge for photoinjectors
- average current up to several mA is desireable
- novel III-V semiconductor with direct & wide band gap (3.4 eV)



2. GaN (Cs)

GaN & its characteristics

- high QE (~40%)
- working wavelength range of 150 nm- 400 nm
- negative electron affinity (NEA) → only with Cs
- High robustness: resitant to vacuum contamination
- Good storage: ~3 years under nitrogen atmosphere



Eg= 3.4 eV

cesium activation & NEA

- Mg doping is necessary
 - → increases diffusion length of e⁻ to surface
- activation with monolayer of Cs
 - → work function near surface is lowered below vacuum level (NEA)

[S. Uchiyama., et al., APL 86, 103511 (2005)]

GaN

photocathode

R&D

Table 1: Comparison of different photocathodes for SRF Guns

Property [Unit]	K ₂ CsSb	Cs ₂ Te	GaAs	Cu	Mg	GaN
harmonic *	2	4	2	4	4	3
λ [nm]	532	266	532	266	266	365
QE [%]	8	5	5	1.4E-2	0.5	~40
lifetime [hours]	4	> 100	~58	> 1 year	> 1 year	several years
response time [ps]	prompt	prompt	< 40	prompt	prompt	???
vacuum tolerance	poor	very good	poor	excellent	excellent	excellent
* For drive lacer, Nd. VAG output at 1061 pm						

* For drive laser: Nd:YAG, output at 1064 nm

Introduction to the physics of electron emission, K.L.Jensen, 2017, p. 444 f. Bazarov, Ivan V. et al. 2009. "Thermal Emittance and Response Time Measurements of a GaN Photocathode." Journal of Applied Physics 105(8).

4. Ongoing working plan

analytical chemistry

activation chamber

cathode bodies for SRF Gun I

cathode for Cs, Te

cathode for GaN

- SEM, TEM & AFM
- XRD, XPS & EDX
- RBS & AES

PL & QE

- cleaning process of GaN wafer? (analytic surface chemistry)
- compare GaN on different substrate material
- chemical stability under intensive laser?

Modification of activation chamber

easy measurement of activated GaN

detect contaminations/ lattice impurities

transfer from glove box without air exposure

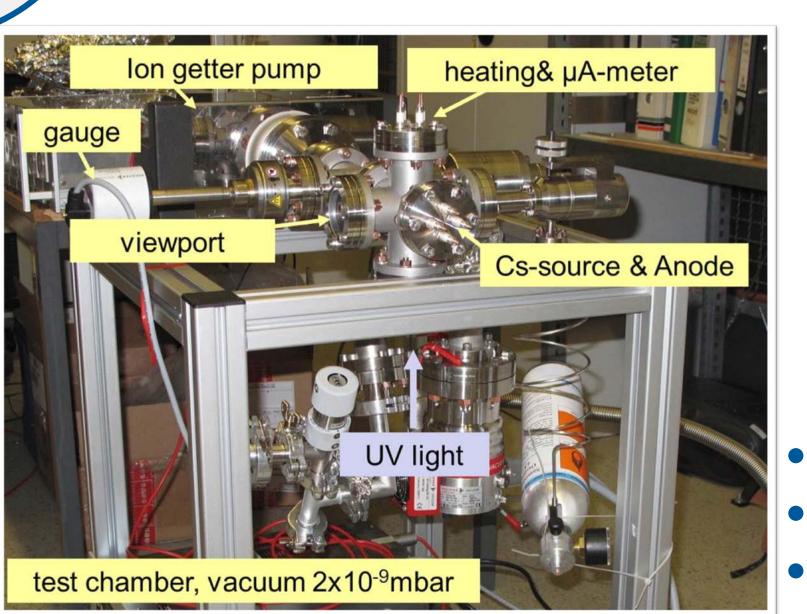
processing in SRF Gun II?

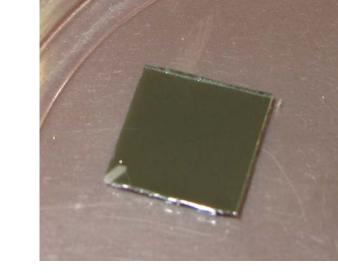
combination with SEM/EDX

sample changement

easy handling

3. First activation treatments





GaN on sapphire

sample pre-treatment

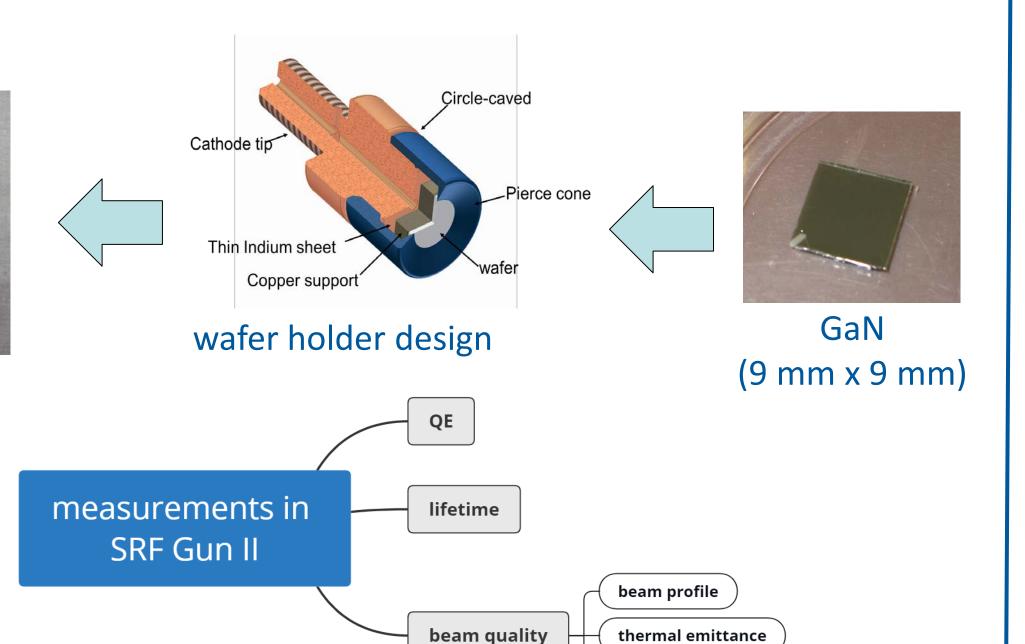
Ultrasonic bath in MeOH (3 min)

etch in H₂SO₄: H₂O₂ (4:1) (5 min)

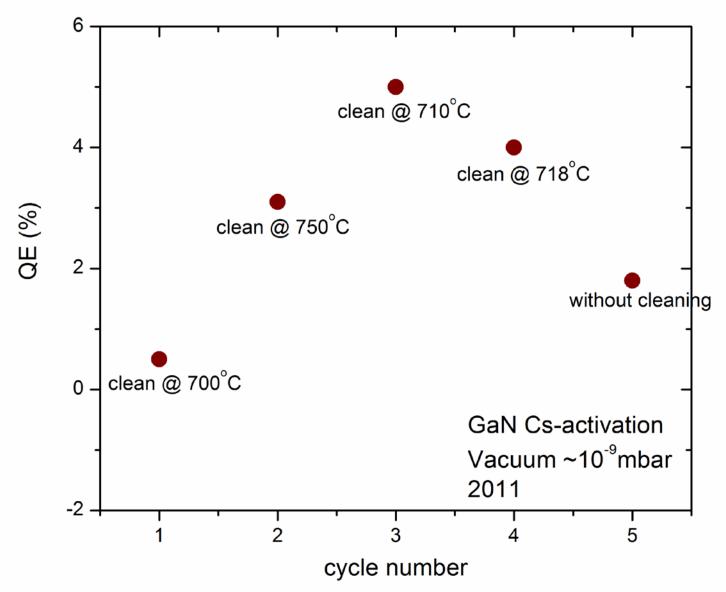
rinse with H₂O and MeOH



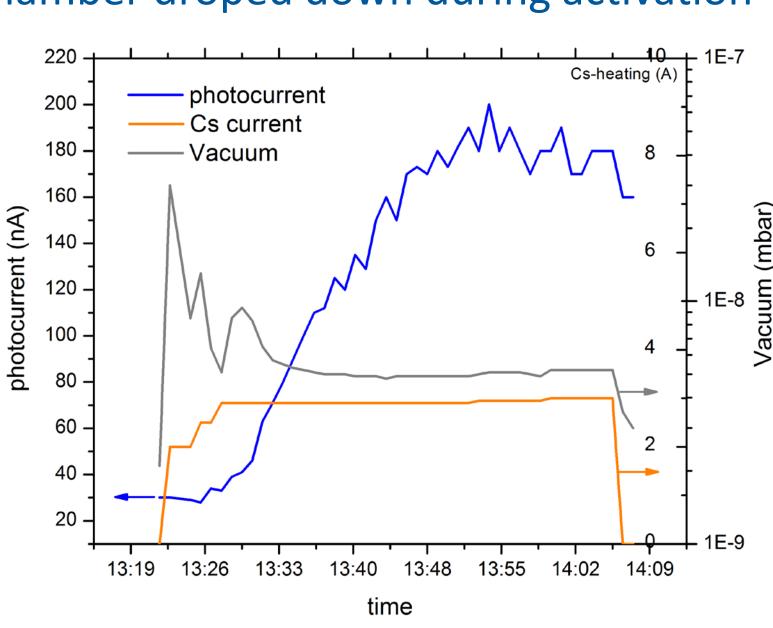
- Pre-heat treatment to remove absorbed residual gases on GaN surface
- activated with Cs-dispenser (SAES) to achieve the NEG surface
- background vacuum in the test chamber droped down during activation



dark current



710°C seems suitable for the heat cleaning of GaN. 5% is the best QE in the activation tests on the same sample



The process of the 4th cycle activation. 262 nm laser is used for the process detect. 500 V bias is added on the anode

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